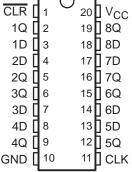
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- **Controlled Baseline**
 - One Assembly/Test Site, One Fabrication
- **Enhanced Diminishing Manufacturing** Sources (DMS) Support
- **Enhanced Product-Change Notification**
- Qualification Pedigree[†]
- **Supports Mixed-Mode Signal Operation** (5-V Input and Output Voltages With 3.3-V V_{CC})
- Typical V_{OI P} (Output Ground Bounce) <0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- **Supports Unregulated Battery Operation** Down to 2.7 V
- **Buffered Clock and Direct-Clear Inputs**
- Individual Data Input to Each Flip-Flop
- Ioff Supports Partial Power-Down-Mode Operation

† Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Latch-Up Performance Exceeds 500 mA Per JESD 17
- **ESD Protection Exceeds JESD 22**
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)

PW OR NS PACKAGE (TOP VIEW) CLR 1Q **∏** 2 19**∏** 8Q



description/ordering information

This octal D-type flip-flop is designed specifically for low-voltage (3.3 V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.

The SN74LVTH273 is a positive-edge-triggered flip-flop with a direct clear (\overline{CLR}) input. Information at the data (D) inputs meeting the setup-time requirements is transferred to the Q outputs on the positive-going edge of the clock pulse. Clock triggering occurs at a particular voltage level and is not related directly to the transition time of the positive-going pulse. When the clock (CLK) input is at either the high or low level, the D-input signal has no effect at the output.

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

This device is fully specified for partial power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

ORDERING INFORMATION

TA	PACK	AGE [‡]	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
-40°C to 85°C	TSSOP - PW	Tape and reel	SN74LVTH273IPWREP	LH273EP	
-55°C to 125°C	SOP - NS	Tape and reel	SN74LVTH273MNSREP	LVTH273EP	

[‡] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

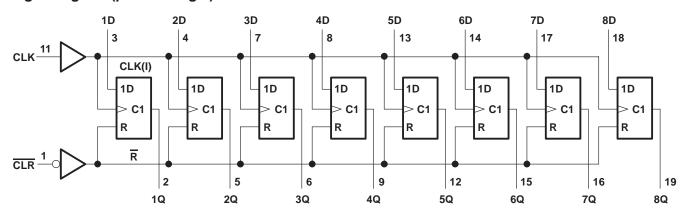


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FUNCTION TABLE (each flip-flop)

	INPUTS	OUTPUT	
CLR	CLK	D	Q
L	Х	Χ	L
Н	\uparrow	Н	Н
Н	\uparrow	L	L
Н	H or L	Χ	Q_0

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	to 4.6 V
Input voltage range, V _I (see Note 1)	V to 7 V
Voltage range applied to any output in the power-off state, V _O (see Note 1) –0.5	V to 7 V
Voltage range applied to any output in the high state, V _O (see Note 1)0.5 V to V _{CO}	+ 0.5 V
Current into any output in the low state, I _O	128 mA
Current into any output in the high state, IO (see Note 2)	. 64 mA
Input clamp current, I _{IK} (V _I < 0)	-50 mA
Output clamp current, I _{OK} (V _O < 0)	-50 mA
Package thermal impedance, θ _{JA} (see Note 3): NS package 94	4.4°C/W
PW package	83°C/W
Storage temperature range, T _{stg} –65°C t	o 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 - 2. This current flows only when the output is in the high state and $V_O > V_{CC}$.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.
 - 4. Long-term high-temperature storage and/or extended use at maximum recommended operating conditions may result in a reduction of overall device life. See http://www.ti.com/ep_quality for additional information on enhanced plastic packaging.



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recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
Vcc	Supply voltage		2.7	3.6	V
VIH	High-level input voltage		2		V
V _{IL}	Low-level input voltage			8.0	V
VI	Input voltage			5.5	V
IOH	High-level output current		-32	mA	
loL	Low-level output current			64	mA
Δt/Δν	Input transition rise or fall rate			10	ns/V
T On a realizer from a circ to a realizer		SN74LVTH273I		85	00
TA	Operating free-air temperature	SN74LVTH273M	-55	125	°C

NOTE 5: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. See the TI application report, Implications of Slow or Floating CMOS Inputs (SCBA004).

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

			SN74	LVTH27	31	SN74	LVTH273	M			
PARAMETER		TEST CONDIT	MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	UNIT		
VIK		$V_{CC} = 2.7 \text{ V, I}_{I} = -18 \text{ mA}$				-1.2			-1.2	V	
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V, I}_{OH} = 0.00 \text{ V}$	V _{CC} -0.2			V _{CC} -0.2					
VOH		$V_{CC} = 2.7 \text{ V, I}_{OH} = -8 \text{ mA}$	2.4			2.4			V		
		$V_{CC} = 3 \text{ V}, I_{OH} = -32 \text{ mA}$	2			2					
		V 0.7.V	I _{OL} = 100 μA			0.2			0.2		
		V _{CC} = 2.7 V	$I_{OL} = 24 \text{ mA}$			0.5			0.5		
VOL		I _{OL} = 16 mA			0.4			0.4	V		
		VCC = 3 V	$I_{OL} = 32 \text{ mA}$			0.5			0.5		
			I _{OL} = 64 mA			0.55			0.55		
		$V_{CC} = 0 \text{ or } 3.6 \text{ V}, V_{I} = 5.5 \text{ V}$	V			10			12		
	Control inputs	$V_{CC} = 3.6 \text{ V}, V_{I} = V_{CC} \text{ or } 0$			±1			±2			
I _I	Data in mate	V 00V	VI = VCC			1			1	μΑ	
	Data inputs	V _{CC} = 3.6 V	V _I = 0			-5			-5	-5	
l _{off}		$V_{CC} = 0$, V_I or $V_O = 0$ to 4	.5 V			±100			±100	μΑ	
		V 2V	V _I = 0.8 V	75			75				
11/15-51-51	Data inputs	VCC = 3 V	V _I = 2 V	-75			-75			μΑ	
I _{l(hold)} Data inputs		$V_{CC} = 3.6 \text{ V}^{\ddagger}, V_{I} = 0 \text{ to } 3.6$			500 -750			500 -750	μΛ		
		$V_{CC} = 3.6 \text{ V}, I_{O} = 0,$	Outputs high			0.19			0.19		
Icc		$V_I = V_{CC}$ or GND	Outputs low			5			5	mA	
ΔICC§	ì	$V_{CC} = 3 \text{ V to } 3.6 \text{ V, One inp}$ Other inputs at V_{CC} or GN				0.2			0.2 m		
Ci		V _I = 3 V or 0			4			4		pF	

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$.



[‡] This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

[§] This is the increase in supply current for each input that is at the specified TTL voltage level, rather than VCC or GND.

SN74LVTH273-EP 3.3-V ABT OCTAL D-TYPE FLIP-FLOP WITH CLEAR

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timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

			V _{CC} =	3.3 V 3 V	VCC =	2.7 V	UNIT	
			MIN	MAX	MIN	MAX		
fclock	Clock frequency			150			MHz	
t _W	Pulse duration		3.3		3.3		ns	
	0.1.1	Data high or low before CLK↑	2.3		2.7			
t _{su}	Setup time	CLR high before CLK↑	2.3		2.7		ns	
t _h	Hold time, data high or low after CLK↑		0		0		ns	

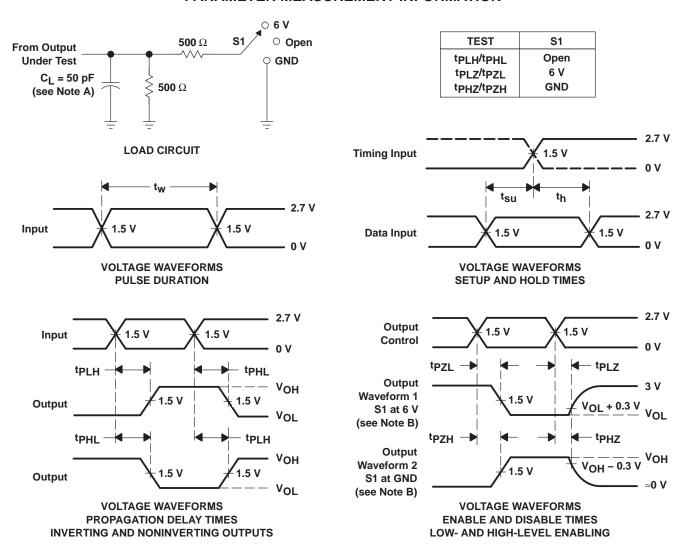
switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

							H273I	SN74LVT	H273M	
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$			V _{CC} = 2.7 V		V _{CC} = 2.7 V		UNIT
	(1141 01)	(0011 01)	MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
f _{max}			150							MHz
tPLH	CLK	A O	1.7	3.2	4.9		5.5		7	
t _{PHL}	CLK	Any Q	1.9	3.2	4.8		5.1		6.6	ns
t _{PHL}	CLR	Any Q	1.6	2.7	4.3		4.7		7	ns

[†] All typical values are at V_{CC} = 3.3 V, T_A = 25°C.



PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50 \ \Omega$, $t_f \leq 2.5 \ ns$.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



PACKAGE OPTION ADDENDUM

10-Dec-2020

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
							(6)				
CLVTH273MNSREPG4	ACTIVE	so	NS	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	LVTH273EP	Samples
SN74LVTH273MNSREP	ACTIVE	so	NS	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	LVTH273EP	Samples
V62/04674-02YE	ACTIVE	so	NS	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	LVTH273EP	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

10-Dec-2020

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN74LVTH273-EP:

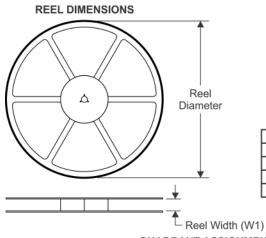
NOTE: Qualified Version Definitions:

Catalog - TI's standard catalog product

PACKAGE MATERIALS INFORMATION

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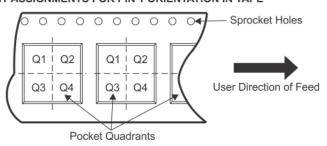
TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

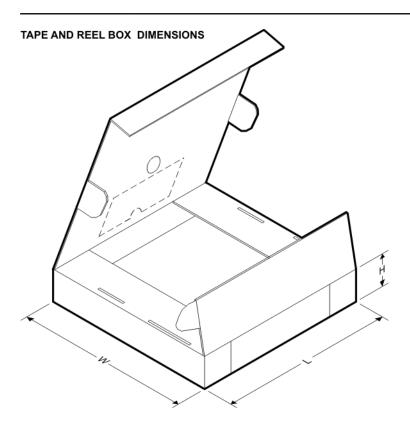
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVTH273MNSREP	SO	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
SN74LVTH273MNSREP	SO	NS	20	2000	367.0	367.0	45.0	

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